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CCS L 90

SJ

**INDUSTRY STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

SJ/T 10454-2020

Replacing SJ/T 10454-1993

**Dielectric paste for multilayer lay out of thick film hybrid
integrated circuits**

厚膜混合集成电路多层布线用介质浆料

(English Translation)

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What this standard covers

This standard specifies the technical requirements, test methods, inspection rules, packaging, storage and transportation of dielectric pastes for thick film hybrid integrated circuit multilayer wiring (hereinafter referred to as pastes). This standard applies to dielectric pastes for thick film hybrid integrated circuit multilayer wiring that match gold, palladium and silver conductor pastes.

Document data

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Standards quoted by this document

GB/T 2423 2-2008; GB/T 2423.3 2006; GB/T 2423.22-2012; SJ/T 11512-2015